

**FXO/DAA Design
Using IXYS Integrated Circuits Division
OptoMOS[®] Components**

1. Introduction

IXYS Integrated Circuits Division OptoMOS components can be applied to a variety of DAA telephone line interface designs suitable for many applications.

This application note includes a collection of DAA circuits that use IXYS Integrated Circuits Division OptoMOS components. It also includes a primer on DAA circuit fundamentals and listings of OptoMOS DAA design resources.

These circuits show the versatility of the OptoMOS line of components. You can select just the portions of a DAA you need to use, and select the level of integration required to minimize component count, cost, and printed-circuit board space.

Note: Circuits presented in this application note assume a +5 Vdc power supply.

2. DAA Fundamentals

2.1 Telephone Network Connection

Devices that connect to telephone networks generally require a data access arrangement circuit (DAA). The DAA provides the physical connection between the telephone line and the device, while, at the same time, providing the necessary electrical isolation that allows devices designed with it to meet the requirements of applicable regulatory agencies. Examples of some common devices are telephones and modems found in set-top boxes, point-of-sale terminals, answering machines, vending equipment, and metering equipment.

Isolation of host equipment from the telephone network assures that no harm to the network occurs due to a device malfunction in the customer premises equipment (CPE). Without isolation, a device connected to the network could damage central office equipment and endanger telephone company personnel if it failed. Additionally, if a high voltage transient is applied to the telephone line from an outside source (a lightning-induced transient, for example), the device and user are generally protected by the high electrical isolation that a DAA provides.

2.2 DAA Functions

In addition to the primary function of isolation, a DAA circuit must also provide the following functions while meeting stringent regulatory requirements:

1. Line termination
2. 2-to-4 wire conversion (hybrid function)
3. Ring detection
4. Signal coupling
5. Monitoring on-hook transmissions (display functions like caller-ID)
6. Surge/transient protection

2.2.1 Surge Protection

The surge protection block protects the CPE from damage, most likely lightning induced transients or power-cross events. Protection circuit topology varies and is determined by the system's reliability criteria.

2.2.2 Switchhook

The switchhook controls the off-hook and on-hook condition. When the switchhook is closed, the device is off-hook and current flows from the central office battery through the switchhook and DC termination circuit. This current is known as the loop current.

2.2.3 DC Termination

The DC termination presents a low DC resistance across tip and ring when the DAA is off-hook, but maintains a very high AC impedance that will not interfere with the AC termination of the DAA. The DC termination also has a bridge rectifier that allows the circuit to operate even if the tip and ring leads are inadvertently reversed.

2.2.4 Ring Detection

The ring detection block connects across the tip and ring terminals and is used to monitor the line for an incoming ring signal. The circuit is AC coupled in order to meet low on-hook current draw requirements. The ring detection circuit requires an isolation barrier to isolate the telephone line from the CPE power supply.

2.2.5 Isolation and Signal Coupling

The isolation and signal coupling block couples the AC signal to and from the host system while maintaining linearity and providing electrical isolation in excess of 1500 V_{RMS}.

2.2.6 Hybrid

The hybrid network is also known as the 2-to-4 wire converter. Since both transmit and receive signals are on the same telephone line pair at the same time (full duplex), a mechanism is required such that the transmitted signal from the device is removed or minimized at the device receive path. In a voice application, poor rejection of the transmit signal into the receive path is apparent as “talker echo.” For data applications, poor rejection of the transmit signal in the receive path can cause poor data throughput. The loss from transmit path to receive path is known as transhybrid loss, measured in decibels.

2.3 Optional DAA Circuits

In addition to the basic functions described above, DAA circuits may be required to perform one or more of these optional functions:

2.3.1 Loop Current Detection

Some PBX systems require reading the current being drawn from the phone line. Using a DAA to detect loop current is shown in the Loop Current Detection section ([Section 4.1 on page 10](#)).

2.3.2 Display Services (Caller ID)

Display services such as caller ID require monitoring the telephone line in the on-hook state. The establishment of an on-hook AC path for display services signals is shown in the Caller ID Detection section ([Section 4.2 on page 12](#)).

2.3.3 Line Use Detection

Managing the use of the telephone line in either the on-hook or off-hook states can be a DAA requirement for some CPE devices. See the 911 Function section ([Section 5.1 on page 14](#)), and the APOH Function section ([Section 5.2 on page 16](#)) for more information.

2.3.4 Reverse Battery Condition

Some telephone networks, especially private ones, use reverse-battery type signalling for direct-inward-dialing (DID). A reverse battery detection circuit is shown in the Detecting Loop Reverse-Battery Condition on a Telephone Line section ([Section 7 on page 20](#)).

2.4 DAA Circuits

- *North American/JATE DAAs* 4
 - Using 1-Form-A Switchhook - LCA110 and LDA101* 4
 - Using TS117 for Switchhook and Ring Detect* 6
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Table 1: Part List for Figure 1

Quantity	Reference Designator	Description
1	R1	47 k Ω , 1/8 W
1	R2	8.2 k Ω , 1/4 W
1	R3	68 k Ω , 1/4 W
1	R4	100 k Ω , 1/4 W
1	R5	10 Ω , 1/4 W
1	R6	470 Ω , 1/4 W
1	C1	0.47 μ F, 250 V
1	C2	10 μ F, 50 V, Tantalum
1	C3	10 μ F, 25 V, Tantalum
1	C4	optional (<i>see Section 6 on page 18</i>)
1	T1	Midcom 82096 transformer
1	BR1	400 PIV bridge rectifier
1	U1	IXYS Integrated Circuits Division LCA110
1	U2	IXYS Integrated Circuits Division LDA101
2	ZD1, ZD2	18 V Zener diode
2	ZD3, ZD4	5.1 V Zener diode
1	ZD5	18 V, 1/2 W Zener diode
1	Q1	FZT605 Zetex Darlington
1	SP1	P3100SBL Littelfuse SIDACtor device
1	F1	1.25 A, 250 V fuse
1	D1	1N4001

Table 2: Part List for Figure 2

Quantity	Reference Designator	Description
1	R1	47 k Ω , 1/8 W
1	R2	8.2 k Ω , 1/4 W
1	R3	68 k Ω , 1/4 W
1	R4	100 k Ω , 1/4 W
1	R5	10 Ω , 1/4 W
1	R6	470 Ω , 1/4 W
1	C1	0.47 μ F, 250 V
1	C2	10 μ F, 50 V, Tantalum
1	C3	10 μ F, 25 V, Tantalum
1	C4	optional (<i>see Section 6 on page 18</i>)
1	T1	Midcom 82096 transformer
1	BR1	400 PIV bridge rectifier
1	U1	IXYS Integrated Circuits Division TS117
2	ZD1, ZD2	18 V Zener diode
2	ZD3, ZD4	5.1 V Zener diode
1	ZD5	18 V, 1/2 W Zener diode
1	Q1	FZT605 Zetex Darlington
1	SP1	P3100SBL Littelfuse SIDACtor device
1	F1	1.25 A, 250 V fuse
1	D1	1N4001

Table 3: Part List for Figure 3

Quantity	Reference Designator	Description
1	R1	47 k Ω , 1/8 W
1	R2	8.2 k Ω , 1/4 W
1	R3	51 k Ω , 1/4 W
1	R4	22 k Ω , 1/4 W
1	R5	10 Ω , 1/4 W
1	R6	470 Ω , 1/4 W
1	C1	0.47 μ F, 250 V
1	C2	10 μ F, 50 V, Tantalum
1	C3	10 μ F, 25 V, Tantalum
1	C4	optional (<i>see Section 6 on page 18</i>)
1	T1	Midcom 82096 transformer
1	U1	IXYS Integrated Circuits Division ITC135 or ITC137
2	ZD1, ZD2	18 V Zener diode
1	SP1	P3100SBL Littelfuse SIDACtor device
1	F1	1.25 A, 250 V fuse

Table 4: Part List for Figure 4

Quantity	Reference Designator	Description
2	R1, R8	47 k Ω , 1/8 W
1	R2	8.2 k Ω , 1/4 W
1	R3	51 k Ω , 1/4 W
1	R4	22 k Ω , 1/4 W
1	R5	10 Ω , 1/4 W
1	R6	470 Ω , 1/4 W
1	R7	60 Ω , 1/4 W
1	C1	0.47 μ F, 250 V
1	C2	10 μ F, 50 V, Tantalum
1	C3	10 μ F, 25 V, Tantalum
1	C4	optional (<i>see Section 6 on page 18</i>)
1	T1	Midcom 82096 transformer
1	U1	IXYS Integrated Circuits Division ITC135 or ITC137
1	U2	IXYS Integrated Circuits Division LDA100
2	ZD1, ZD2	18 V Zener diode
1	SP1	P3100SBL Littelfuse SIDACTor device
1	F1	1.25 A, 250 V fuse

4.2 Caller ID Detection

Figure 5 shows an ITC135/ITC137-based DAA like the one in figure 3 with the addition of a TS117 to handle loop current detection and caller ID (CID) signal processing. For CID processing without loop current detection, substitute CPC1035 or LCA110 for the TS117.

CID signals must be passed by the DAA while the DAA is on-hook. Voice-band FSK CID signals are included after the first ring burst.

This circuit uses the relay portion of the TS117 to pass CID signals as follows:

1. The host processor detects the first ring burst from the $\overline{\text{RING}}$ output of the ITC135/ITC137.
2. The host processor asserts $\overline{\text{CID}}$ after the first ring, completing an AC signal path from C1 through the relay in the TS117, and coupling the CID signal through the transformer and hybrid to the CODEC or data pump.
3. After receiving the CID signal, the host processor de-asserts $\overline{\text{CID}}$, preserving on-hook telephone line characteristics.

Figure 5. Caller ID Detection Using TS117

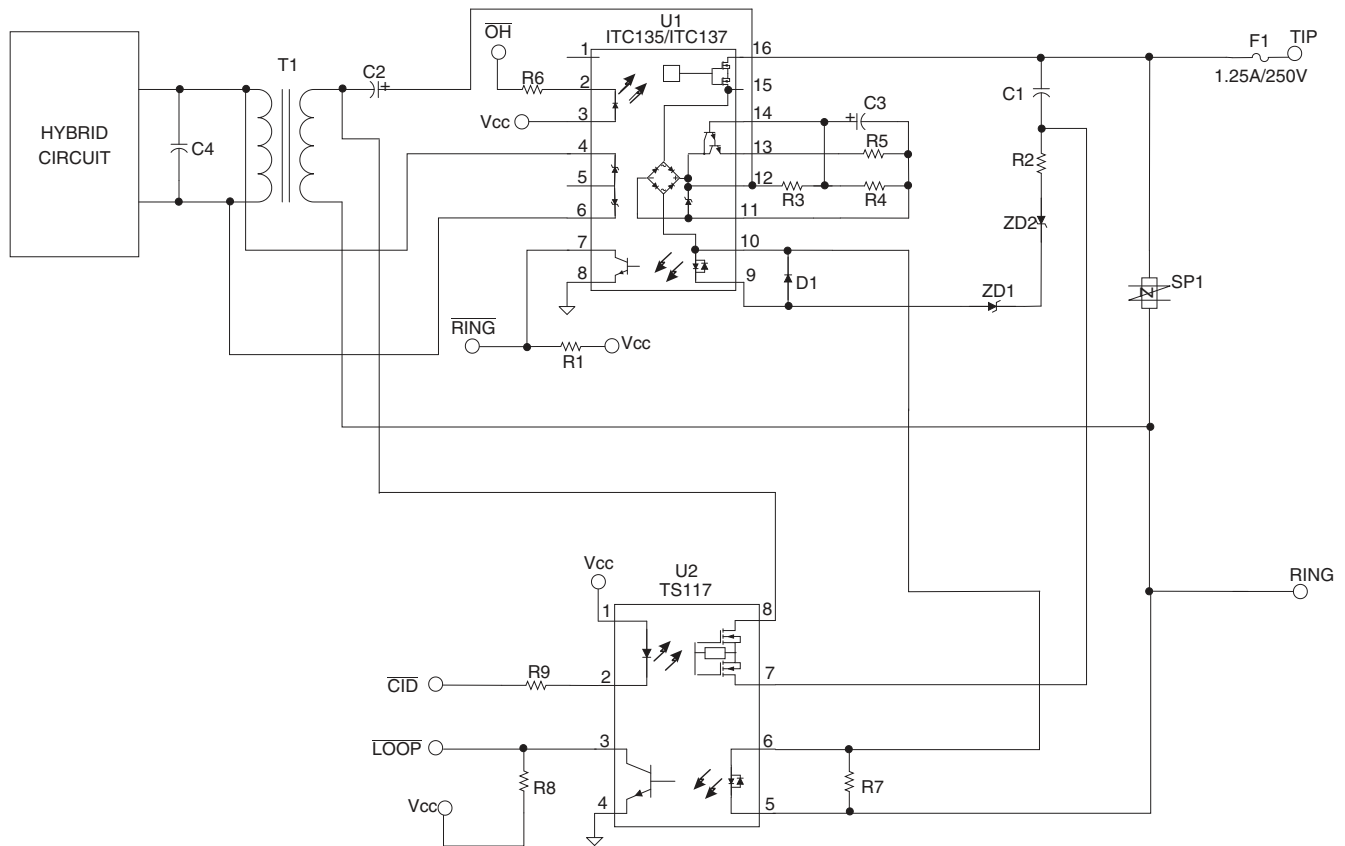


Table 5: Part List for Figure 5

Quantity	Reference Designator	Description
2	R1, R8	47 k Ω , 1/8 W
1	R2	8.2 k Ω , 1/4 W
1	R3	51 k Ω , 1/4 W
1	R4	22 k Ω , 1/4 W
1	R5	10 Ω , 1/4 W
1	R6	470 Ω , 1/4 W
1	R7	60 Ω , 1/4 W
1	C1	2.2 μ F, 50 V
1	C2	10 μ F, 50 V, Tantalum
1	C3	10 μ F, 25 V, Tantalum
1	C4	optional (<i>see Section 6 on page 18</i>)
1	T1	Midcom 82096 transformer
1	U1	IXYS Integrated Circuits Division ITC117P
1	U2	IXYS Integrated Circuits Division ITC135/ITC137
2	ZD1, ZD2	18 V Zener diode
1	SP1	P3100SBL Littelfuse SIDACTor device
1	F1	1.25 A, 250 V fuse

5. Phone Line Use Detection

DAA circuits may need help managing the use of the telephone line to which they are connected by monitoring for another parallel-connected telephone off-hook while the modem is in either the off-hook or on-hook states. These functions are often called the 911 function (monitoring for another telephone going off-hook while the DAA is off-hook) and another phone off-hook or APOH (monitoring for another phone using the line while the DAA is on-hook).

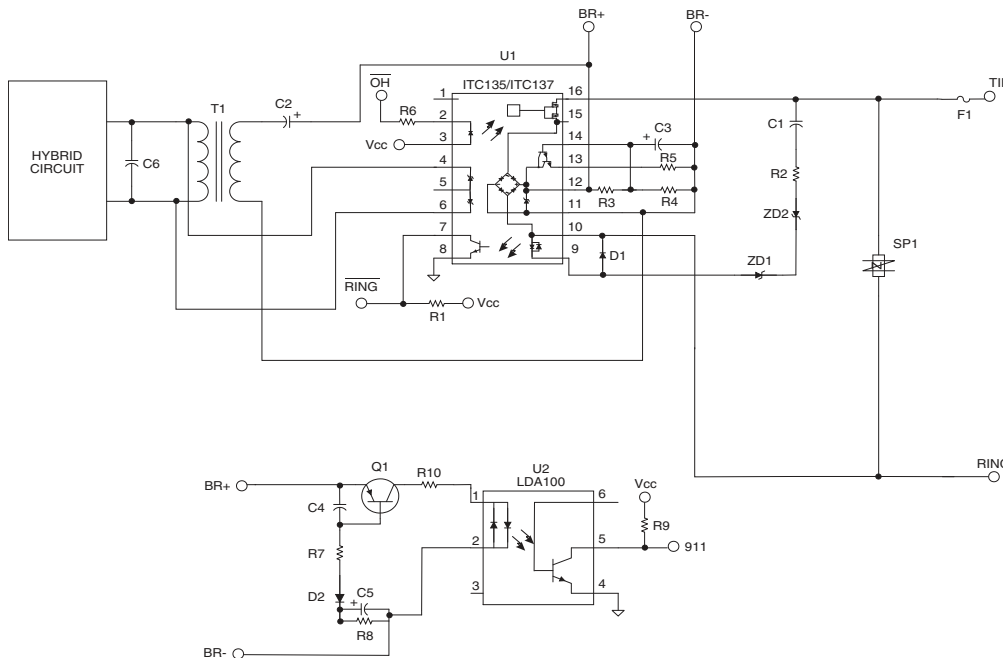
Bear in mind that these are two similar but different situations that must be handled differently in the DAA.

5.1 911 Function

Consider the case of the satellite set-top box. The STB periodically dials out to transfer information with the service provider. During this call, other devices (like telephones) connected to the telephone line cannot be used until the information transfer concludes and the DAA in the STB hangs up. This leads to the potentially dangerous situation where an emergency occurs during this period where the user needs to dial "911." The DAA in the STB must have the capability to detect when another phone or device tries to use the telephone line while the STB is already using the line.

Figure 6 shows an IXYS Integrated Circuits Division OptoMOS DAA with a 911 function detector.

Figure 6. 911 Function



With the DAA off-hook, capacitor C5 charges through the PN emitter-base junction of transistor Q1. With Q1 on, current flows through the LED in U2, holding the 911 output off.

When another phone tries to use the telephone line, the tip to ring voltage drops, causing the base and emitter voltages of Q1 to drop. With D2 now reverse-biased, the charge in capacitor C5 maintains the previous off-hook voltage level on the cathode of D2 momentarily. Q1 turns off, shutting off the LED in U2, and causing a logic high pulse at the 911 output. After C5 discharges through R8, Q1 conducts, the LED in U2 turns on, and the 911 output returns low. The width of the output pulse is determined by the time constant of C5 and R8.

The system controller must detect this pulse and tell the DAA to release the telephone line (go on-hook).

Table 6: Part List for Figure 6

Quantity	Reference Designator	Description
2	R1, R9	47 k Ω , 1/8 W
1	R2	8.2 k Ω , 1/4 W
1	R3	51 k Ω , 1/4 W
1	R4	22 k Ω , 1/4 W
1	R5	10 Ω , 1/4 W
1	R6	470 Ω , 1/4 W
1	R7	1 k Ω , 1/4 W
2	R8, R10	10 k Ω , 1/4 W
1	C1	0.47 μ F, 50 V
1	C2	10 μ F, 50 V, Tantalum
1	C3	10 μ F, 25 V, Tantalum
1	C4	0.1 μ F, 50 V
1	C5	10 μ F, 16 V
1	C6	optional (<i>see Section 6 on page 18</i>)
1	T1	Midcom 82096 transformer
1	U1	IXYS Integrated Circuits Division ITC135/ITC137
1	U2	IXYS Integrated Circuits Division LDA100
1	D1	1N4001
2	ZD1, ZD2	18 V Zener diode
1	SP1	P3100SBL Littelfuse SIDACtor device
1	F1	1.25 A, 250 V fuse

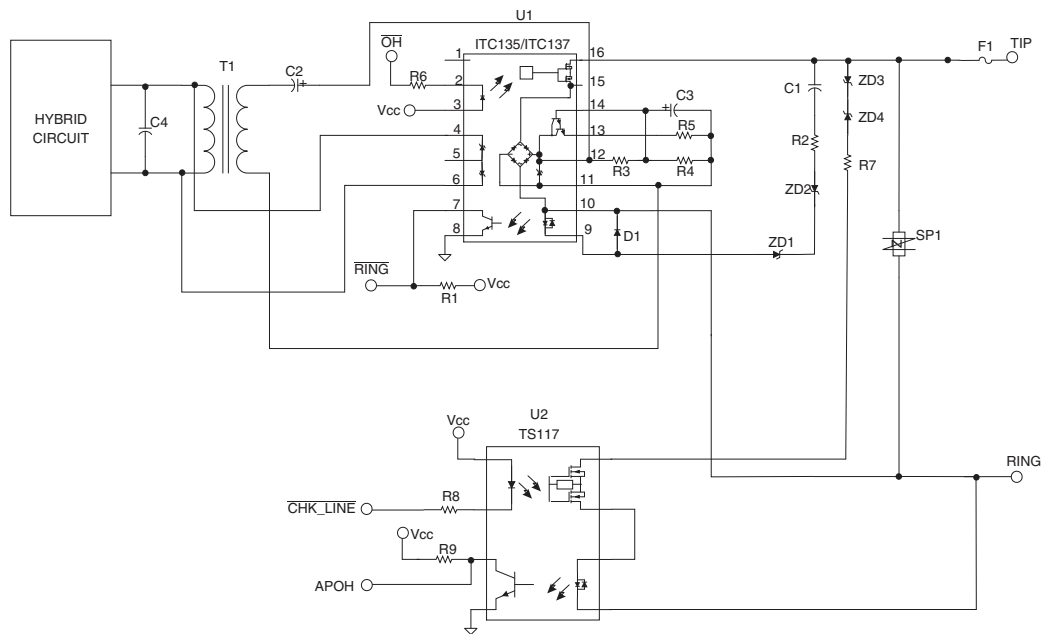
5.2 APOH Function

While the 911 DAA function allows for release of a phone line when a parallel-connected phone is taken off-hook (see Section 5.1 on page 14), another circuit is required to see if another device has taken the phone line off-hook before the DAA tries to connect. This function is often called APOH (another phone off-hook).

An APOH circuit can take advantage of the voltage drop that occurs on a telephone line when any parallel-connected device takes the line off-hook. In North America, for instance, the tip to ring voltage difference is usually greater than 40 Vdc when the telephone is not in use, but, when the line is in use, the tip to ring voltage is somewhere between 4 to 11 Vdc.

Figure 7 shows an IXYS Integrated Circuits Division OptoMOS DAA with an APOH detector.

Figure 7. APOH Detection Using TS117



To check whether or not the line is in use, the system controller asserts $\overline{\text{CHK_LINE}}$, closing the relay portion of U2, an IXYS Integrated Circuits Division TS117. ZD3 and ZD4 prevent current flow in this part of the circuit when the tip to ring voltage drops between 4 to 11 Vdc. Two 18 V Zener diodes prevent current flow and make the circuit insensitive to telephone line polarity.

With another telephone device offhook, no current flows through the APOH branch of the circuit, turning the optocoupler in U2 off. This sets the APOH output high, indicating an APOH condition. With no external telephone devices off-hook the Zeners conduct. Current in the APOH detector circuit causes APOH to go low. With APOH low, the host device can assert $\overline{\text{OH}}$ and use the telephone line.

Selecting the value of R7 is critical. R7 must be a high enough value to reduce telephone line loop current below the threshold normally considered as an off-hook condition by the central office equipment. Yet R7 must also be a low enough value to provide sufficient current to the optocoupler in U2 to keep it on when there is not another parallel-connected telephone off-hook.

After checking the line for APOH, the system controller must de-assert $\overline{\text{CHK_LINE}}$ for normal DAA operation. See IXYS Integrated Circuits Division's application note AN-123, *Using CYG2911 and TS117 in APOH (911) Circuits* for more information on component value selection.

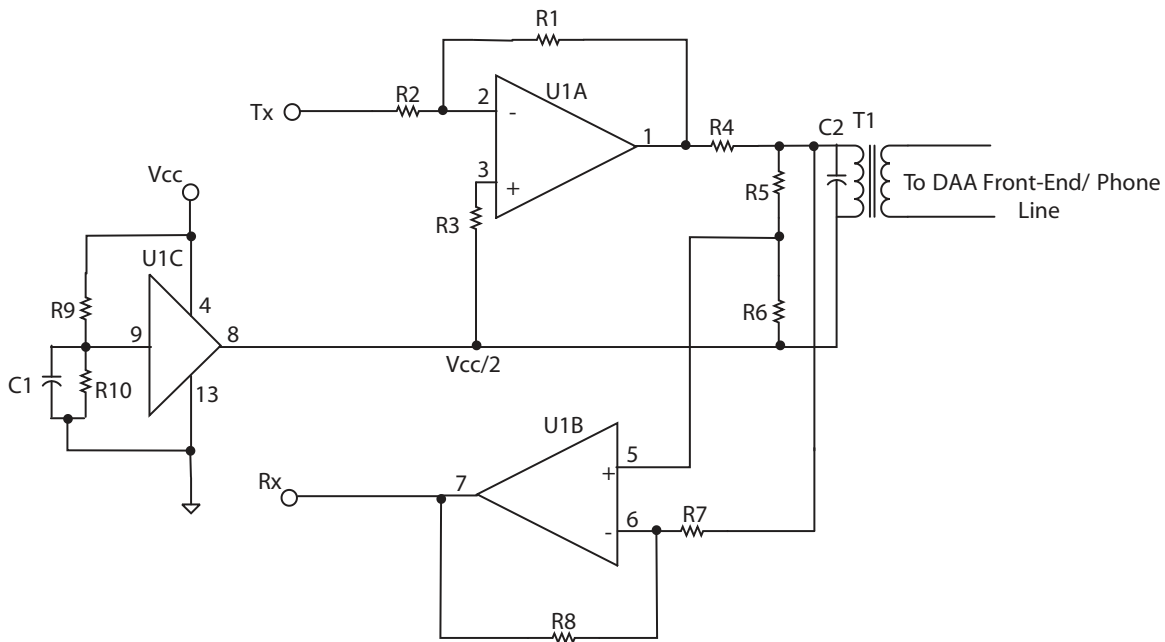
Table 7: Part List for Figure 7

Quantity	Reference Designator	Description
2	R1, R9	47 k Ω , 1/8 W
1	R2	8.2 k Ω , 1/4 W
1	R3	51 k Ω , 1/4 W
1	R4	22 k Ω , 1/4 W
1	R5	10 Ω , 1/4 W
1	R6	470 Ω , 1/4 W
1	R7	51 k Ω , 1/4 W
1	R8	470 Ω , 1/4 W
1	C1	0.47 μ F, 250 V
1	C2	10 μ F, 50 V, Tantalum
1	C3	10 μ F, 25 V, Tantalum
1	C4	0.1 μ F, 50 V
1	C5	10 μ F, 16 V
1	C6	optional (<i>see Section 6 on page 18</i>)
1	T1	Midcom 82096 transformer
1	U1	IXYS Integrated Circuits Division ITC135/ITC137
1	U2	IXYS Integrated Circuits Division TS117
2	ZD1, ZD2, ZD3, ZD4	18 V Zener diode
1	SP1	P3100SBL Littelfuse SIDACTor device
1	F1	1.25 A, 250 V fuse
1	D1	1N4001

6. DAA Hybrid Circuit

Figure 8 shows a typical hybrid (two-wire to four-wire conversion) circuit. The signal labelled TX in the diagram is the signal transmitted from the CODEC or modem data pump to the telephone line.

Figure 8. Typical Hybrid Circuit



The signal is amplified by U1A to account for the transducer loss incurred through R4 and T1, typically 6 dB when connected to a properly matched 600 Ω line. The value of R4 is determined by the specific transformer in use and often specified by the transformer manufacturer.

U1C is a low output-impedance buffer that reproduces the voltage at pin 9. R8 and R9 are matched so that the reference Voltage $V_{CC}/2$ allows hybrid operation from a single supply.

U1 is specified as a rail-to-rail amplifier to accommodate large signal swings.

R5 and R6 present part of the transmit signal to U1B. This signal cancels the transmit signal (V1) from the receive path in U1B as follows:

$$V_{RX} = \left(\frac{R7 + R8}{R5 + R6}\right)\left(\frac{R6}{R7}\right)V1 - \left(\frac{R8}{R7}\right)V2$$

Using the values from the part list for the circuit in figure 8, where R7 = 20 kΩ, R8 = 40 kΩ, R5 = 15 kΩ, and R6 = 15 kΩ, the formula becomes:

$$V_{RX} = (1.5)(V1) - (2)(V2)$$

Setting V_{RX} for 0, with no transmitted signal appearing at RX yields:

$$0 = (1.5)(V1) - (2)(V2)$$

Solving for V2 in terms of V1 yields:

$$V_2 = \left(\frac{1.5}{2}\right)(V_1)$$

Substituting into the original equation yields:

$$V_{RX} = (1.5)(V_1) - (2)\left(\frac{1.5}{2}\right)(V_1) = 0$$

While this equation shows complete cancellation of the transmit signal in the receive path, practical considerations, such as component tolerances and variations in telephone line length, suggest a real-world cancellation of between 15 dB to 30 dB.

Capacitor C2 compensates for leakage inductance effects from the transformer at high frequencies. This capacitor may improve or degrade transhybrid loss, depending on the transformer. Test the circuit to optimize the value for C2 for transhybrid loss.

Table 8: Part List for Figure 8

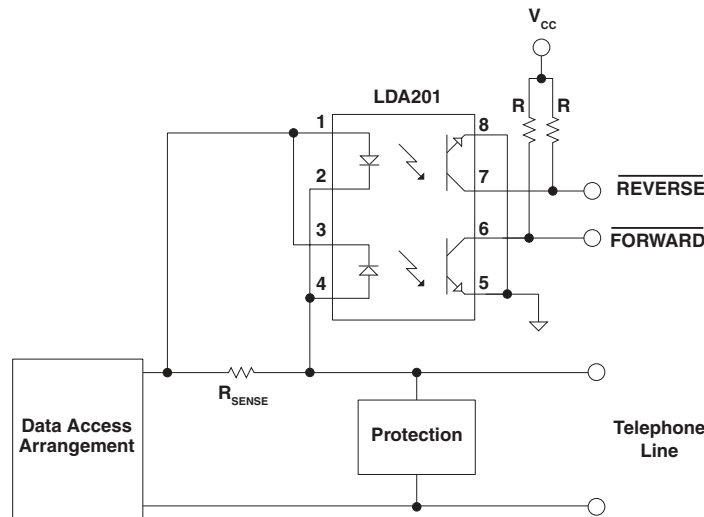
Quantity	Reference Designator	Description
1	R1	20 kΩ, 1/8 W
1	R2	10 kΩ, 1/4 W
1	R3	6.8 kΩ, 1/4 W
1	R4	530 Ω, 1/4 W
2	R5, R6	15 kΩ, 1/4 W
1	R7	20 kΩ, 1/4 W
1	R8	40 kΩ, 1/4 W
2	R9, R10	47 kΩ, 1/4 W
1	C1	0.1 μF, 50 V
1	C2	see text
1	U1	TS 925 op amp, ST Microelectronics or similar

7. Detecting Loop Reverse-Battery Condition on a Telephone Line

Some equipment connected to telephone networks must be able to detect reversal of the battery feed voltage. Some direct-inward-dialing (DID) systems use loop reverse-battery signalling. See ANSI T1.405-1996 for more information.

One requirement of loop reverse-battery condition detectors is the ability to distinguish the direction of battery current. Figure 9 shows a loop reverse-battery detection circuit using an IXYS Integrated Circuits Division LDA201 that provides forward and reverse output signals.

Figure 9. Loop Reverse-Battery Detection Using LDA201



Tip is normally positive with respect to ring in telephone loops. The nominal open voltage from the telephone network is -48 Vdc. In this circuit, the value of R_{SENSE} allows a threshold current before forward or reverse sensing.

Given the nominal forward voltage of the LEDs in the LDA201 of 1.2 V, a value of $120\ \Omega$ for R_{SENSE} provides a 10 mA threshold value, where

$$R_{SENSE} = \frac{V_F}{I}$$

or,

$$R_{SENSE} = \frac{1.2}{10mA} = 120\ \Omega$$

When loop current exceeds 10 mA with normal polarity, $\overline{FORWARD}$ is asserted. When the loop current exceeds 10 mA with reversed polarity, $\overline{REVERSE}$ is asserted. The forward voltage specification for the LDA201 varies from 0.9 V to 1.4 V and is affected by temperature. With R_{SENSE} at $120\ \Omega$, detection threshold currents will vary from 7.5 mA to 11.7 mA.

Set the values of the pull-up resistors (R) based on the minimum current transfer ratio of the LDA201 and the minimum LED current for the application according to the specifications in the LDA201 data sheet.

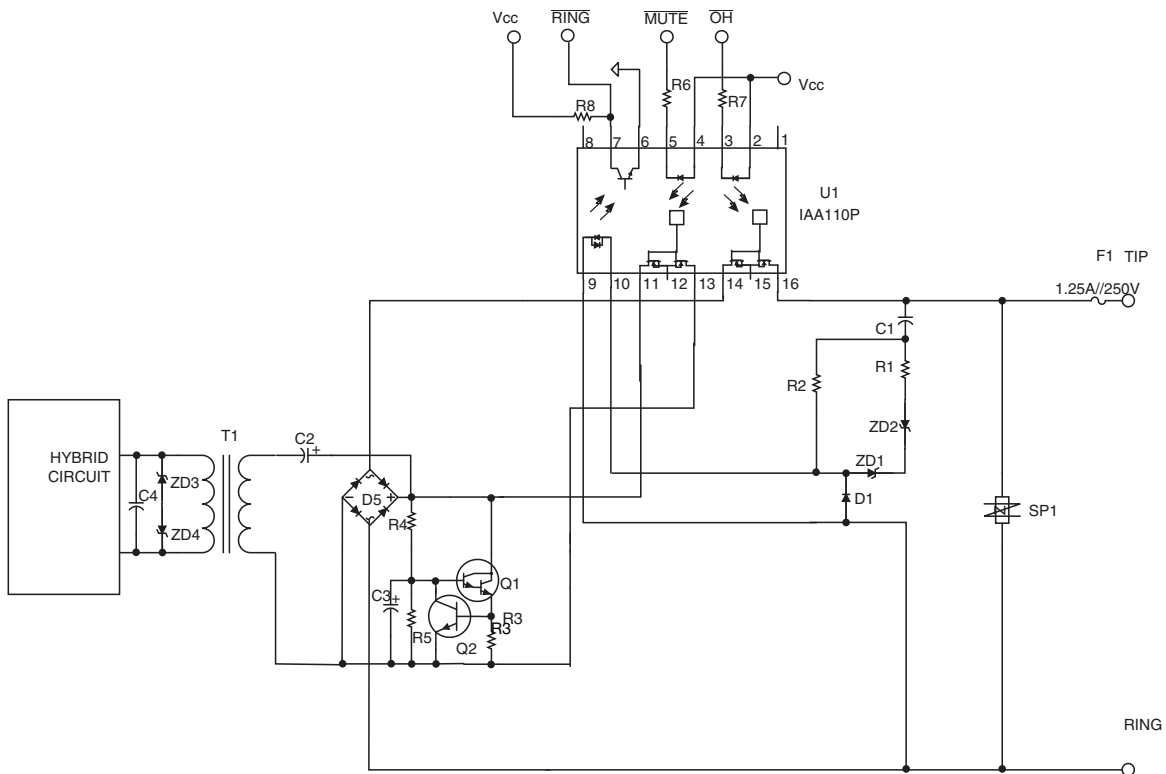
The LEDs in the LDA201 are rated for 100 mA maximum current, so current limited resistors in series with the LEDs are not needed.

8. European Type DAA Circuits

The circuit in Figure 10 can be populated for many of the telephone systems that require compliance to European Directive 1999/5/EC from March 9, 1999 and the now obsolete TBR-21. Diagrams are also included here for specific implementations required in certain areas.

The IAA110P was chosen for this design because it can function as the switchhook, ring detector, and as a mute relay.

Figure 10. European Type DAA Using IAA110P



The mute relay can be used both for low-impedance (fast) pulse dialing and to meet the transient off-hook requirements of some systems. Typically, MUTE is asserted in conjunction with OH and held for 50 milliseconds.

One important functional difference between this circuit and the circuits described earlier is telephone line loop-current limiting. Many European systems require limiting the loop current to 60 mA.

Loop current limiting is accomplished with Q2 and R3 in this circuit. With R3 set to 10 Ω and the V_{BE} of Q2 of 0.6 V, line current is limited to 60 mA.

Limiting the current in this way leads to the possibility of tip to ring voltages as high as 40 V, which infers that power dissipation in Q1 could be as high as 2.4 Watts. Q1 requires adequate heat sinking to account for this high power level.

Table 9: Part List for Figure 10

Quantity	Reference Designator	Description
1	R1	20 k Ω , 1/4 W
1	R2	100 k Ω , 1/8 W
1	R3	10 Ω , 1/8 W
1	R4	47 k Ω , 1/8 W
1	R5	68 k Ω , 1/8 W
2	R6, R7	470 Ω , 1/8 W
1	R8	47 k Ω , 1/8 W
1	C1	0.33 μ F, 250 V
1	C2	10 μ F, 50 V Tantalum
1	C3	10 μ F, 25 V Tantalum
1	C5	optional (<i>see Section 6 on page 18</i>)
1	T1	Midcom 82096 transformer
1	U1	IXYS Integrated Circuits Division IAA110P
2	ZD1, ZD2	33 V Zener
1	SP1	P3100SBL Littelfuse SIDACTor device
1	F1	1.25 A, 250 V fuse
1	D2	1N4001
1	BR1	400 V bridge rectifier
1	Q1	FZT604 NPN Darlington, Zetex
1	Q2	BC846 NPN Transistor, 65 V

8.1 European Type DAA with Metering Filter

Some areas, like Germany, use telephone service metering signals to collect billing information. The circuit in Figure 11 is similar to the one in Figure 10, but adds an LC tank circuit at the tip connection to filter out the metering signal (16 kHz in the case of Germany) and preserve DAA DC characteristics while off-hook.

Figure 11. TBR-21 Type DAA With Metering Filter Using IAA110P

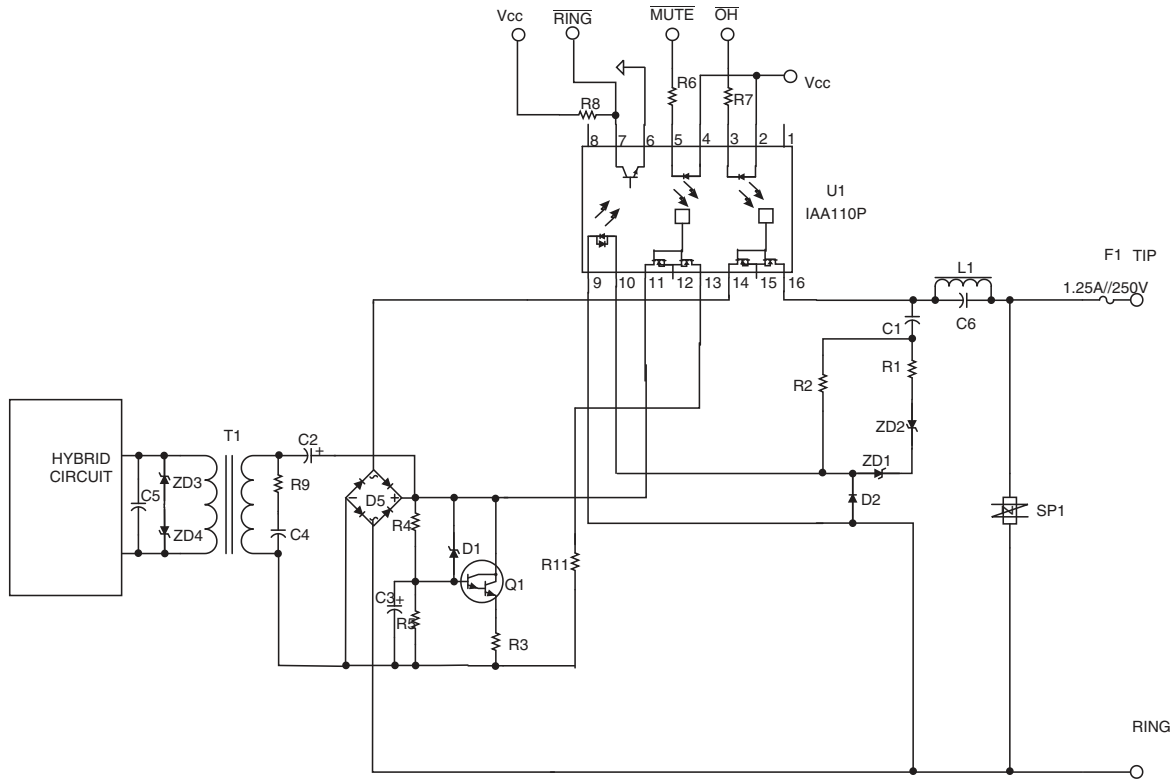


Table 10: Part List for Figure 11

Quantity	Reference Designator	Description
1	R1	20 k Ω , 1/4 W
1	R2	100 k Ω , 1/8 W
1	R3	10 Ω , 1/8 W
1	R4	120 k Ω , 1/8 W
1	R5	68 k Ω , 1/8 W
2	R6, R7	470 Ω , 1/8 W
1	R8	47 k Ω , 1/8 W
1	R9	180 Ω , 1/4 W
1	R11	68 Ω , 1/4 W
1	C1	0.47 μ F, 250 V
1	C2	10 μ F, 50 V Tantalum
1	C3	10 μ F, 25 V Tantalum
1	C4	0.082 μ F, 50 V
1	C5	optional (<i>see Section 6 on page 18</i>)
1	C6	0.29 μ F, 50 V
1	T1	Midcom 82096 transformer
1	U1	IXYS Integrated Circuits Division IAA110P
1	L1	3.3 mH inductor, 100 mA dc current
2	ZD1, ZD2	20 V Zener
1	SP1	P3100SBL Littelfuse SIDACtor device
1	F1	1.25 A, 250 V fuse
1	L1	3.3 mH inductor, 100 mA
1	D1	8.2 V Zener, 1/4 W
1	D2	1N4001
1	BR1	400 V bridge rectifier
1	Q1	FZT604 NPN Darlington, Zetex

Table 11: Part List for Figure 12

Quantity	Reference Designator	Description
1	R1	10 k Ω , 1/4 W
1	R2	100 k Ω , 1/8 W
1	R3	10 Ω , 1/8 W
1	R4	68 k Ω , 1/8 W
1	R5	100 k Ω , 1/8 W
2	R6, R7	470 Ω , 1/8 W
1	R8	47 k Ω , 1/8 W
1	R9	820 Ω , 1/8 W
1	C1	0.47 μ F, 250 V
1	C2	10 μ F, 50 V Tantalum
1	C3	10 μ F, 25 V Tantalum
1	C4	0.056 μ F, 50 V
1	C5	optional (<i>see Section 6 on page 18</i>)
1	T1	Midcom 82096 transformer
1	U1	IXYS Integrated Circuits Division IAA110P
2	ZD1, ZD2	33 V Zener
1	SP1	P3100SBL Littelfuse SIDACtor device
1	F1	1.25 A, 250 V fuse
1	D1	8.2 V Zener, 1/4 W
1	D2	1N4001
1	BR1	400 V bridge rectifier
1	Q1	FZT604 NPN Darlington, Zetex

9. Circuit Layout Considerations

IXYS Integrated Circuits Division strongly recommends that engineers designing a DAA circuit using OptoMOS components become familiar with all regulatory and safety requirements for such devices. In particular, IEC950 and UL1950 contain relevant and useful information. FCC part 68.3, TBR-21, and ETSI EG201 121 also provide useful information.

Although written specifically for IXYS Integrated Circuits Division's LITELINK™ products, application note AN-146, *Guidelines for Effective LITELINK Designs*, contains information useful to the OptoMOS DAA designer.

Remember that component placement and printed-circuit board layout are critical to building compliant, safe products.

10. OptoMOS Design Resources

IXYS Integrated Circuits Division's web site has a wealth of information useful for designing with its products, including application notes and reference designs. Product data sheets also contain additional application and design information. See the following links:

Application Note AN-114: *IITC117P Integrated Telecom Circuit*.

For additional information please visit our web site at: www.ixysic.com

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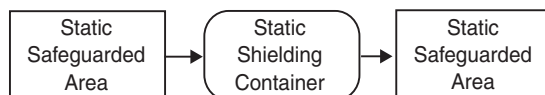
Handling MOS Devices

Static Discharge

Metal Oxide Semiconductor (MOS) devices have gained broad acceptance in telecommunications. This includes use of n-channel (NMOS) transistors, p-channel (PMOS) transistors, or both (complementary or CMOS) transistors. Most IXYS IC Division devices are fabricated using CMOS techniques, but some use PMOS. In any case, MOS circuits require special attention in design and handling because of their susceptibility to damage through buildup of static charges and the currents that occur during discharge.

Whether alone or mounted in circuit boards, MOS ICs are subject to buildup of static charges and damaging discharges. Voltage of several hundred volts can affect these devices, while one or two thousand volts will certainly cause harm. Five hundred volts can easily be generated by a person walking around or moving in a chair, and thousands of volts can be generated by the simple act of pulling out and tearing off a piece of transparent tape. Under these circumstances, precautions must be taken to limit the potential for damage to costly IC devices. MOS ICs should be handled in static-protected or "safeguarded" areas. Such areas include ionized air flow over nonconducting surfaces. When not in these areas, ICs should be kept in static shielded containers. ICs must be handled in safeguarded areas (receiving inspection, stores, assembly, and test) and, when moved from area to area, should be protected by shielded containers. Failure to implement procedures of this sort or relaxation of procedures can result in loss of valuable parts, increased production fallout, and higher repair costs.

Static Transmission



CMOS Latchup

Though all ICs are subject to static discharge damage, CMOS ICs can experience another kind of damaging event known as "latchup" or "SCR." In this case, large currents can follow-through the part from the power supply, damaging transistors and interconnections. This occurs when currents are injected into the chip where they were not intended, usually through an I/O pin which has been driven to a voltage outside the supply range by some external device or event. This phenomenon is equivalent to four-layer conduction as used in SCRs, where a semiconductor device is "turned on" by injecting a current into a trigger layer. The device stays "on" until voltage is removed. This is useful in SCR control circuits, but in the case of CMOS ICs they may (1) recover completely after power has been cycled, (2) recover, but act very strangely, or (3) blow up completely. Causes can be inadequate power supply filtering, transient protection, or coincidences of PWB track layout. Static discharge may also trigger latchup.

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Specification: AN-130-R04
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4/10/2014



Parameter	Rating	Units
Breakdown Voltage - BV_{CEO}	30	V_P
Current Transfer Ratio - CTR (typical)	8500	%
Saturation Voltage - $V_{CE(sat)}$	1	V
Input Control Current - I_F	1	mA

Features

- 100mA Continuous Load Rating
- 3750V_{rms} Input/Output Isolation
- Unidirectional Input
- Small 6-Pin Package, Thru-Hole or Surface Mount
- Machine Insertable, Wave Solderable
- Surface Mount Tape & Reel Packaging Available

Applications

- Telecom Switching
- Tip/Ring Circuits
- Modem Switching (Laptop, Notebook, Pocket Size)
- Loop Detect
- Ringing Detect
- Current Sensing

Description

LDA111 is a unidirectional-input optocoupler with a Darlington-transistor output. The LDA111 has a minimum current transfer ratio (CTR) of 300% with a maximum value of 30,000%.

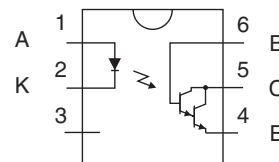
Approvals

- UL Recognized Component: File E76270
- CSA Certified Component: Certificate 1175739
- EN/IEC 60950-1 Certified Component:
TUV Certificate B 09 07 49410 006

Ordering Information

Part Number	Description
LDA111	6-Pin DIP (50/tube)
LDA111S	6-Pin Surface Mount (50/tube)
LDA111STR	6-Pin Surface Mount (1000/Reel)

Pin Configuration



Absolute Maximum Ratings @ 25°C

Parameter	Ratings	Units
Breakdown Voltage	30	V _P
Reverse Input Voltage	5	V
Input Control Current	100	mA
Peak (10ms)	1	A
Power Dissipation		
Input Power Dissipation ¹	150	mW
Phototransistor ²	150	
Isolation Voltage, Input to Output	3750	V _{rms}
Operational Temperature	-40 to +85	°C
Storage Temperature	-40 to +125	°C

¹ Derate linearly 1.33mW / °C

² Derate linearly 2mW / °C

Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at conditions beyond those indicated in the operational sections of this data sheet is not implied.

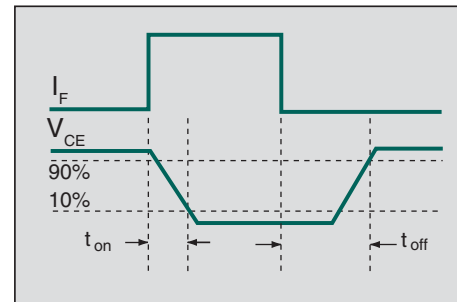
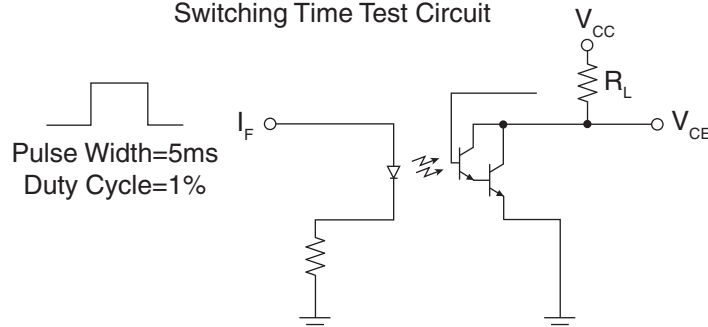
Electrical Characteristics @ 25°C

Parameter	Conditions	Symbol	Min	Typ	Max	Units
Output Characteristics						
Phototransistor Breakdown Voltage	I _C = 100µA	BV _{CEO}	30	85	-	V
Phototransistor Dark Current	V _{CEO} = 5V, I _F = 0mA	I _{CEO}	-	50	500	nA
Saturation Voltage	I _C = 3mA, I _F = 1mA	V _{CE(sat)}	-	-	1	V
Current Transfer Ratio	I _F = 1mA, V _{CE} = 2V	CTR	300	8500	30000	%
Output Capacitance	25V, f = 1MHz	C _{OUT}	-	3	-	pF
Input Characteristics						
Input Control Current	I _C = 3mA, V _{CE} = 2V	I _F	-	0.07	1	mA
Input Voltage Drop	I _F = 5mA	V _F	0.9	1.2	1.4	V
Reverse Input Current	V _R = 5V	I _R	-	-	10	µA
Common Characteristics						
Capacitance, Input to Output	-	C _{I/O}	-	3	-	pF

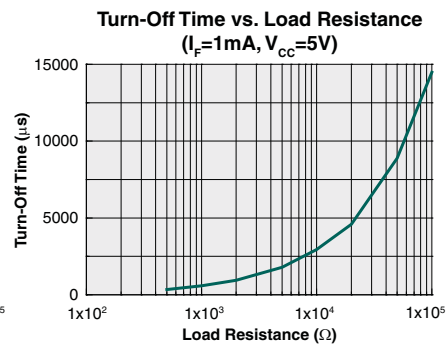
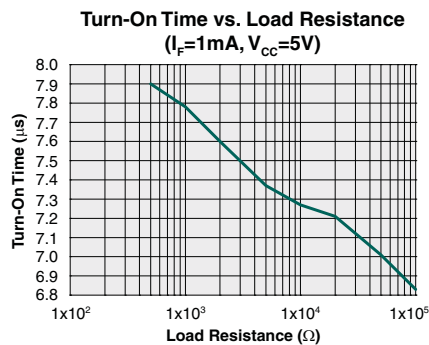
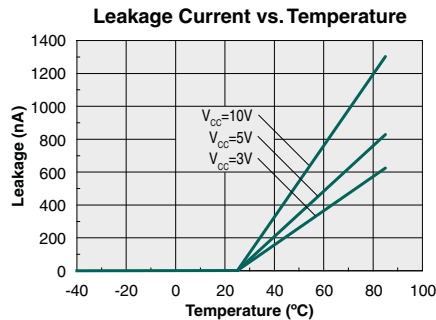
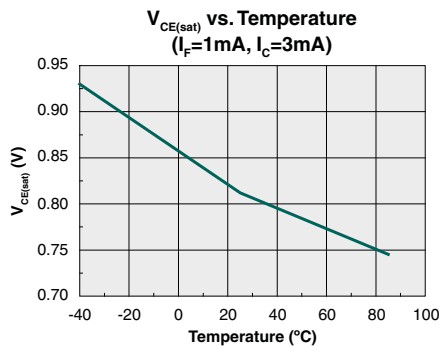
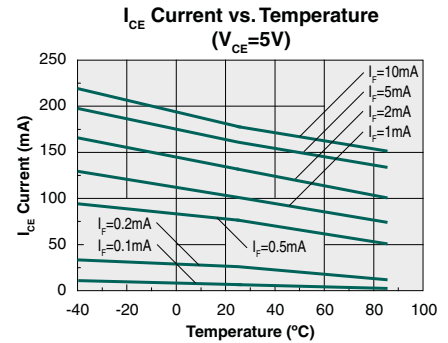
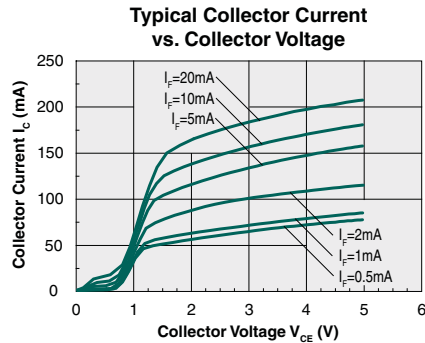
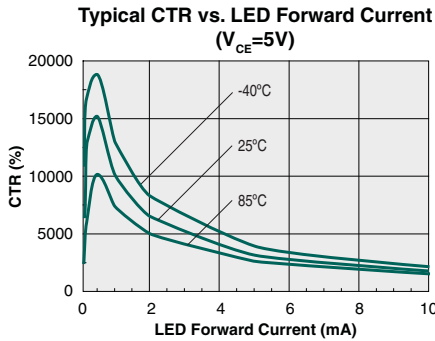
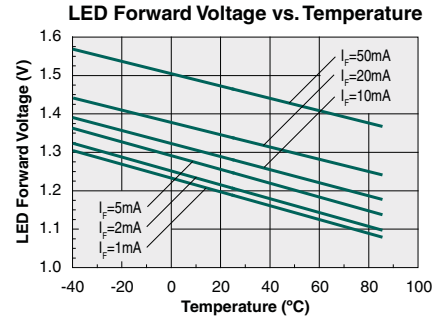
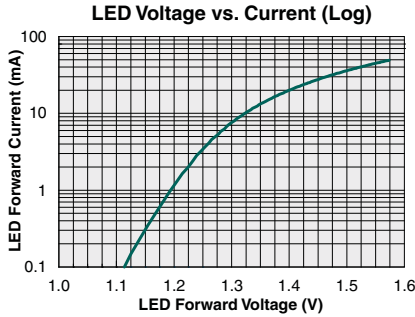
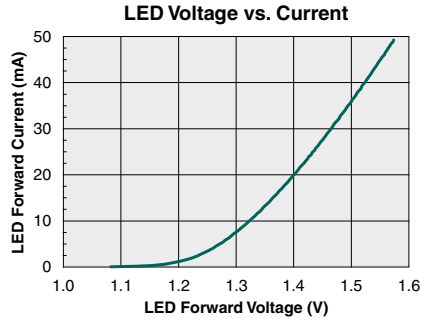
Switching Characteristics @ 25°C

Characteristic	Symbol	Test Condition	Typ	Units
Turn-On Time	t _{on}	V _{CC} =5V, I _F =1mA, R _L =500Ω	8	µs
Turn-Off Time	t _{off}		345	

Switching Time Test Circuit



PERFORMANCE DATA @25°C (Unless Otherwise Noted)*



*The Performance data shown in the graphs above is typical of device performance. For guaranteed parameters not indicated in the written specifications, please contact our application department.

Manufacturing Information

Moisture Sensitivity



All plastic encapsulated semiconductor packages are susceptible to moisture ingress. IXYS Integrated Circuits Division classified all of its plastic encapsulated devices for moisture sensitivity according to the latest version of the joint industry standard, **IPC/JEDEC J-STD-020**, in force at the time of product evaluation. We test all of our products to the maximum conditions set forth in the standard, and guarantee proper operation of our devices when handled according to the limitations and information in that standard as well as to any limitations set forth in the information or standards referenced below.

Failure to adhere to the warnings or limitations as established by the listed specifications could result in reduced product performance, reduction of operable life, and/or reduction of overall reliability.

This product carries a **Moisture Sensitivity Level (MSL) rating** as shown below, and should be handled according to the requirements of the latest version of the joint industry standard **IPC/JEDEC J-STD-033**.

Device	Moisture Sensitivity Level (MSL) Rating
LDA111 / LDA111S	MSL 1

ESD Sensitivity



This product is **ESD Sensitive**, and should be handled according to the industry standard **JESD-625**.

Reflow Profile

This product has a maximum body temperature and time rating as shown below. All other guidelines of **J-STD-020** must be observed.

Device	Maximum Temperature x Time
LDA111 / LDA111S	250°C for 30 seconds

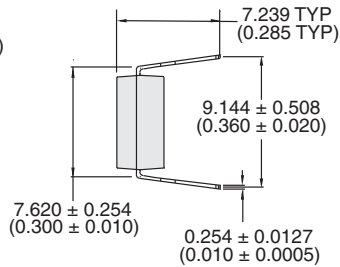
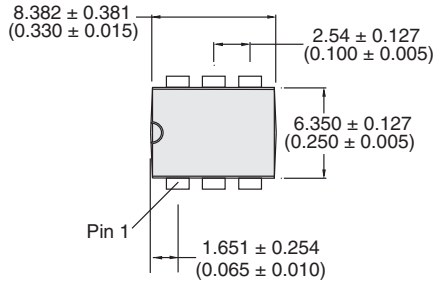
Board Wash

IXYS Integrated Circuits Division recommends the use of no-clean flux formulations. However, board washing to remove flux residue is acceptable. Since IXYS Integrated Circuits Division employs the use of silicone coating as an optical waveguide in many of its optically isolated products, the use of a short drying bake could be necessary if a wash is used after solder reflow processes. Chlorine- or Fluorine-based solvents or fluxes should not be used. Cleaning methods that employ ultrasonic energy should not be used.

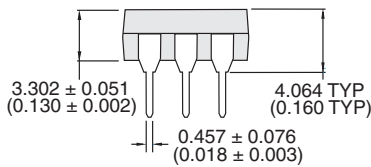
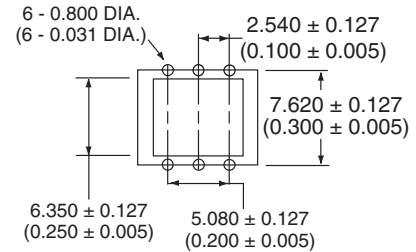


Mechanical Dimensions

LDA111

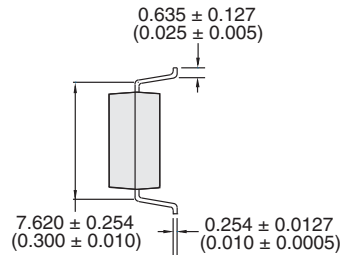
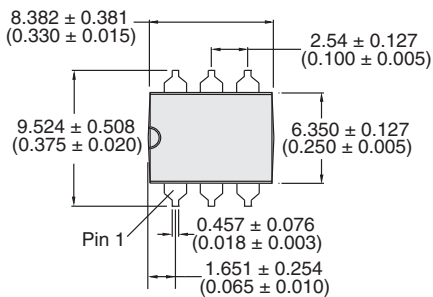


PCB Hole Pattern

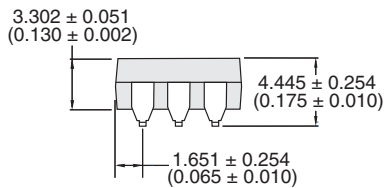
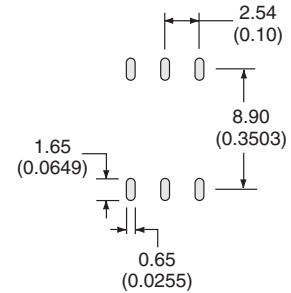


Dimensions
mm
(inches)

LDA111S

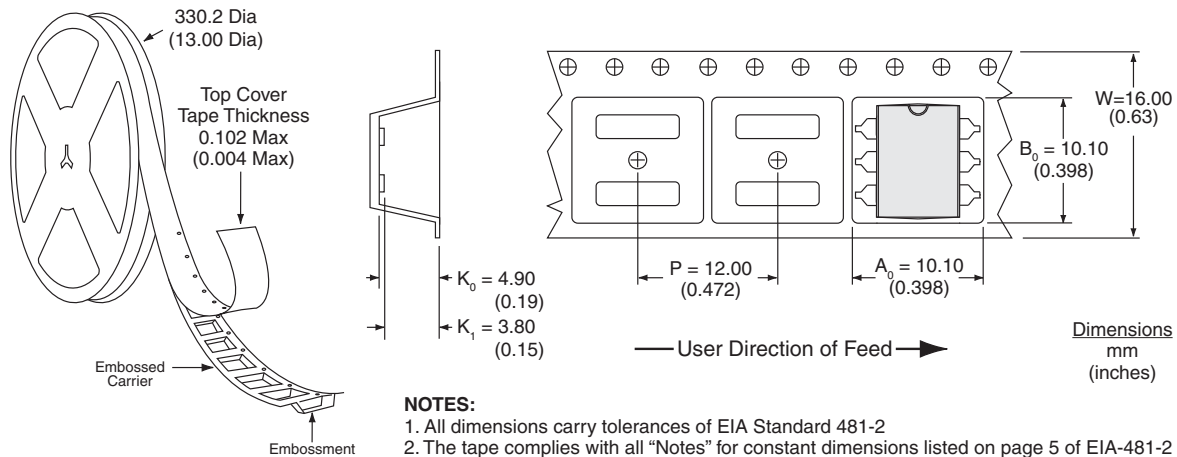


PCB Land Pattern



Dimensions
mm
(inches)

LDA111STR Tape & Reel



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